225 Franklin Street Boston, Massachusetts 02110-2804

Telephone 617 542-5070

Facsimile 617 542-8906

www.fr.com

W.K. Richardson

1859-1951

October 31, 2001

Attorney Docket No.: 13292-007001

Box Patent Application

Commissioner for Patents Washington, DC 20231

Presented for filing is a new original patent application of:

Applicant: HARRY HEDLER, THORSTEN MEYER AND BARBARA VASQUEZ

Title: COMPLIANT RELIEF WAFER LEVEL PACKAGING

Enclosed are the following papers, including those required to receive a filing date under 37 CFR §1.53(b):

	<u>Pages</u>
Specification	10
Claims	3
Abstract	1
Declaration	2 [unsigned]
Drawing(s)	18

Enclosures:

Postcard.

Basic filing fee	\$740
Total claims in excess of 20 times \$18	\$54
Independent claims in excess of 3 times \$84	\$0
Fee for multiple dependent claims	\$0
Total filing fee:	\$794

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Commissioner for Patents October 31, 2001 Page 2

A check for the filing fee is enclosed. Please apply any other required fees or any credits to deposit account 06-1050, referencing the attorney docket number shown above.

If this application is found to be incomplete, or if a telephone conference would otherwise be helpful, please call the undersigned at (617) 542-5070.

Kindly acknowledge receipt of this application by returning the enclosed postcard.

Please send all correspondence to:

FRANK R. OCCHIUTI Fish & Richardson P.C. 225 Franklin Street Boston, Massachusetts 02110-2804

C. EL

Respectfully submitted,

Natal

Natasha C. Us Technology Specialist Reg. No. 44,381

Enclosures

NXU/ava

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APPLICATION

FOR

UNITED STATES LETTERS PATENT

TITLE: COMPLIANT RELIEF WAFER LEVEL PACKAGING

APPLICANT: HARRY HEDLER, THORSTEN MEYER AND BARBARA

VASQUEZ

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